



- Epoxy meets UL-94 V-0 flammability rating
- Halogen free available upon request by adding suffix "HF"
- Moisture Sensitivity Level 1
- High Conductance
- Surface Mount Package Ideally Suited for Automatic Insertion

- : SOT-23
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- Tin plated leads, solderable per J-STD-002 and JESD22-B102
- :

BC856A	3A
BC856B	3B
BC857A	3E
BC857B	3F
BC857C	3G
BC858A	3J B

y j

T B d y

(Ta=25 unless otherwise noted)

V _{CBO}	Collector-Base Voltage BC856 BC857 BC858	-80 -50 -30	V
V _{CEO}	Collector-Emitter Voltage BC856 BC857 BC858	-65 -45 -30	V
V _{EBO}	Emitter-Base Voltage	-5	V
I _C	Collector Current	-0.1	A
P _C	Collector Power Dissipation	200	mW
R _{ΘJA}	Thermal Resistance From Junction To Ambient	625	/W
T _j	Junction Temperature	150	
T	Storage Temperature	-55 to +150	



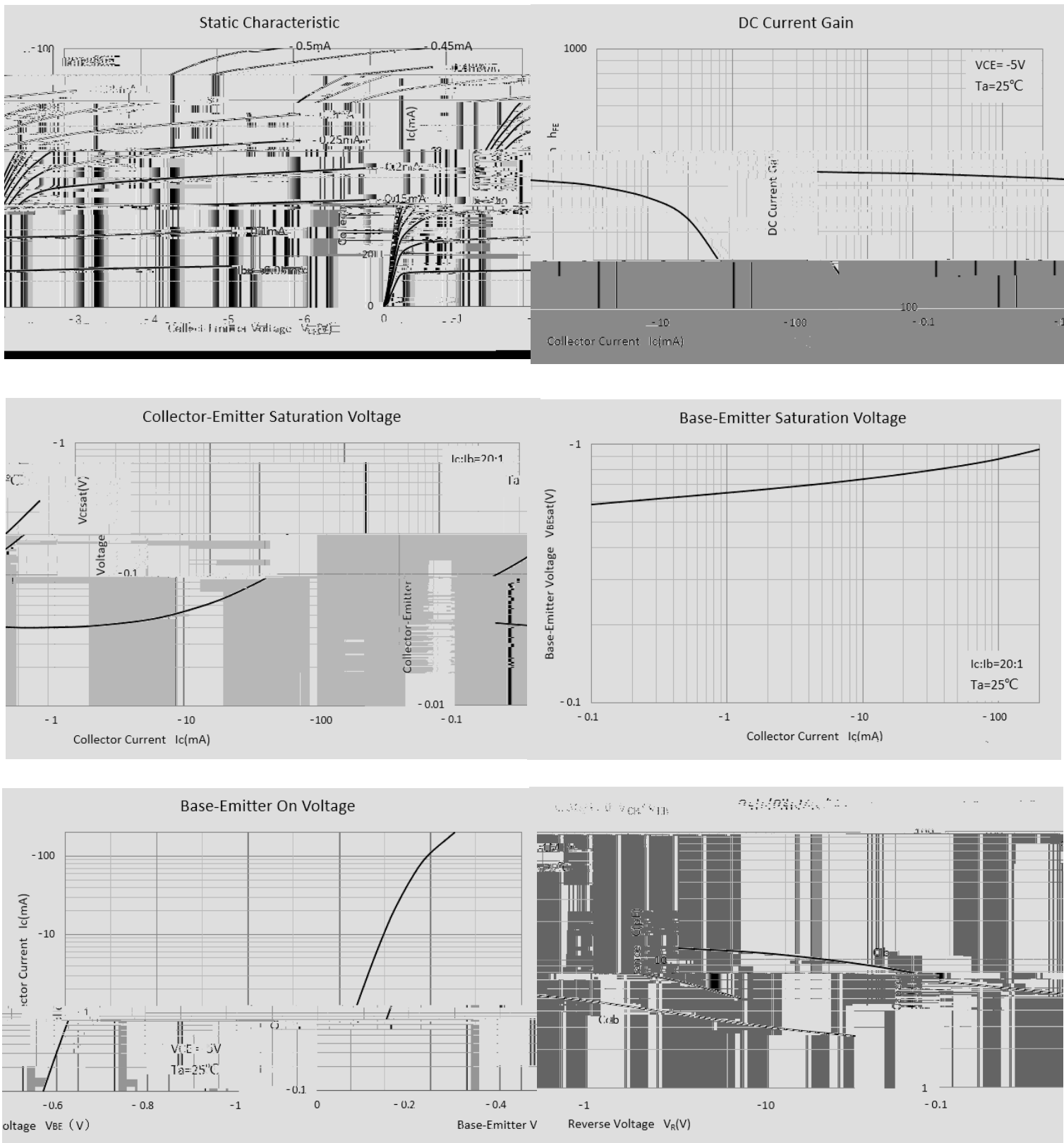
(Ta=25 unless otherwise noted)

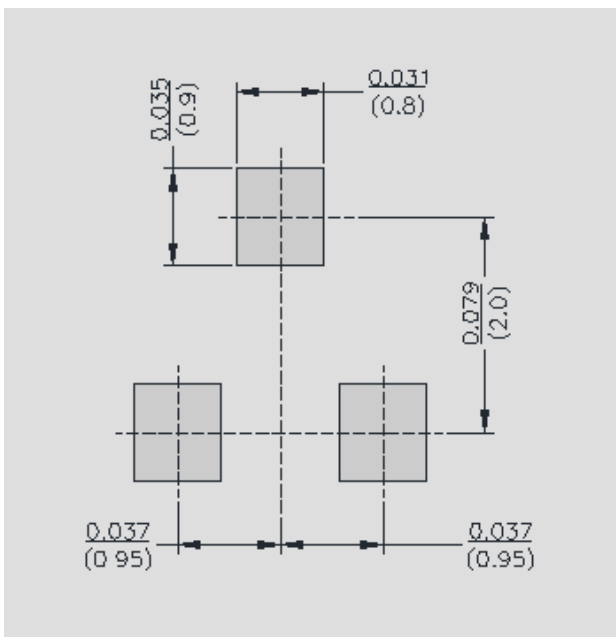
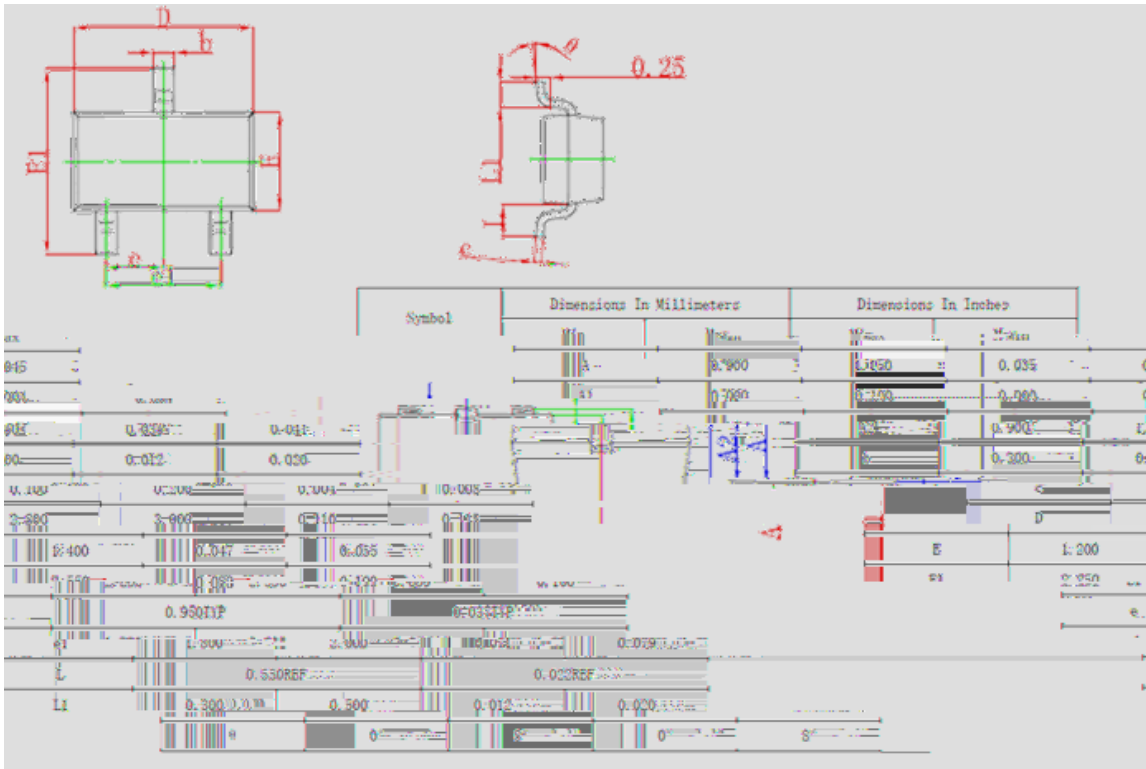
Collector-base breakdown voltage BC856 BC857 BC858	V_{CBO}	$I_C = -10\mu A, I_E = 0$	-80 -50 -30		V
Collector-emitter breakdown voltage BC856 BC857 BC858	V_{CEO}	$I_C = -10mA, I_B = 0$	-65 -45 -30		V
Emitter-base breakdown voltage	V_{EBO}	$I_E = -1\mu A, I_C = 0$	-5		V
Collector-base cut-off current	I_{CBO}	$V_{CB} = -30V, I_E = 0$		-0.1	μA
Emitter-base cut-off current	I_{EBO}	$V_{EB} = -5V, I_C = 0$		-0.1	μA
DC current gain BC856A,857A,858A BC856B,857B,858B BC857C,BC858C	h_{FE}	$V_{CE} = -5V, I_C = -2mA$	125 220 420	250 475 800	
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -100mA, I_B = -5mA$		-0.65	V
Base-emitter saturation voltage	$V_{BE(sat)}$	$I_C = -100mA, I_B = -5mA$		-1.1	V
Transition frequency	f_T	$V_{CE} = -5V, I_C = -10mA$ $f = 100MHz$	100		MHz
Collector-base output capacitance	C_{ob}	$V_{CB} = -10V, f = 1MHz$		4.5	pF

(Example)

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(Typical)







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The product listed herein is designed to be used with ordinary th